

ABSTRACTCONNECTION PAD ARRANGEMENTS FOR ELECTRONIC CIRCUIT
COMPRISING BOTH FUNCTIONAL LOGIC AND FLASH-EEPROM

An integrated circuit (IC1) comprising functional logic (1) and
5 Flash-EEPROM (2) coupled, via mixing devices (IMUX, OMUX), to
connection pads (CP1, CP2), which are arranged into pad arrangements
(PAD: PAD1, PAD2, PAD3, PAD4). Each pad arrangement (PAD) comprises
two juxtaposed connection pads (CP1, CP2) interconnected electrically and
having substantially the same design. In this way, many "probing" are
10 possible on a same pad arrangement, while probing at most two times each
connection pad thereof.. By probing at most two times on a connection pad,
a good "bondability" of the pad is assured. This is particularly useful in the
present case of combined functional logic and the Flash-EEPROM where
three probings are generally required for the flash test of the EEPROM, the
15 digital test of the functional logical and the analog test of the latter. In a
preferred embodiment, the integrated circuit (IC2) comprises a first set of
dedicated connection pads (PAD10, PAD11, PAD12) coupled to the
functional logic (1), and a distinct second set of dedicated connection pads
(PAD21, PAD22) coupled to the Flash-EEPROM (2).

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Fig. 2